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Application Serial No. 09/148,723  
Response to December 16, 2003 Final OA

MI22-981

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application Serial No. .... 09/148,723  
Filing Date ..... September 3, 1998  
Inventor ..... Warren M. Farnworth et al.  
Assignee ..... Micron Technology, Inc.  
Group Art Unit ..... 3729  
Examiner ..... A.D. Tugbang  
Attorney's Docket No. .... MI22-981  
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate

**RESPONSE TO DECEMBER 16, 2003 FINAL OFFICE ACTION**  
**PURSUANT TO 37 C.F.R. §1.116**

To: Mail Stop AF  
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Alexandria, VA 22313-1450

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Responsive to the Final Office Action dated December 16, 2003, Applicant amends and remarks as follows:

**AMENDMENTS**

Underlines indicate insertions and ~~strikeouts~~ indicate deletions.